Plaskon 7060

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

Message:

This material is a reduced-stress epoxy molding compound for the encapsulation of a variety of semiconductor devices ranging from small lead count DIPs to medium lead count PLCCs and SOICs. It was especially developed for balanced end use properties.

General Information			
Features	Semi-conductive Laser marking Good formability Excellent appearance		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	**Nominal Value**	**Unit**	**Test Method**
Specific Gravity	1.83	g/cm³	ASTM D792
Molding Shrinkage - Flow	0.25	%	ASTM D955
Mechanical	**Nominal Value**	**Unit**	**Test Method**
Flexural Modulus	1.52	MPa	ASTM D790
Flexural Strength	0.0138	MPa	ASTM D790
Thermal	**Nominal Value**	**Unit**	**Test Method**
Glass Transition Temperature	155	°C	ASTM E1356
CLTE - Flow	2.0E-5	cm/cm/°C	ASTM D696
Electrical	**Nominal Value**	**Unit**	**Test Method**
Volume Resistivity	1.6E+16	ohms·cm	ASTM D257
Dielectric Strength	16	kV/mm	ASTM D149
Dielectric Constant (1 kHz)	4.00		ASTM D150
Dissipation Factor (1 kHz)	5.0E-3		ASTM D150
Arc Resistance	180	sec	ASTM D495
Flammability	**Nominal Value**	**Unit**	**Test Method**
Flame Rating (3.18 mm)	V-0		UL 94
Oxygen Index	30	%	ASTM D2863

Additional Information
Recommended Storage Temperature: 5°CLife @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 24 monthsLife @ 21°C, defined as not more than 40% loss of spiral flow based on original values.: 5 daysLife @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 2 daysSpiral Flow, 177°C, 1000 psi: 97 cmAutomatic Orifice Viscosity, 175°C, Shear Rate is 157000 sec-1, 1 mm die length, 1/2 mm diameter: 13 to 21 Pascal secRam Follower Gel Time, 177°C: 20 secAsh Content: 73 %Hydrolyzable Halides: <1 ppmCull Hot Hardness, Shore D, 90 sec, 175°C: 80Arc Resistance, 110v AC180 secAll test specimens are transfer molded and post cured for 4 hours at 175°C Linear Thermal Expansion, Alpha 1: 20 cm^-6/cm/°C Linear Thermal Expansion, Alpha 2: 65 cm^-6/cm/°C
Injection instructions

Resin Transfer Molding:
Preheat Temperature: 88 to 99°C
Molding Temperature: 170 to 190°C
Molding Pressure: 750 to 1000 psi
Cure Time, 177°C: 1 to 2min
Post Mold Cure Time, 175°C: 4 hr

Recommended distributors for this material

Susheng Import & Export Trading Co.,Ltd.

Tel: +86 21 5895 8519

Phone: +86 13424755533

Email: sales@su-jiao.com

No. 215, Lianhe North Road, Fengxian District, Shanghai, China